What is claimed is:

1. An Internet thermal data analysis system comprising:

an user end interface to retrieved requests of package parameters from the far-end user who need thermal package analysis via a network;

a storage media;

job database containing several job forms and providing at least one of said job forms for the far-end user to input said package parameters;

a thermal analysis module containing at least one application software to analyze said package parameters;

a package parameter database having package related data stored therein;

a process unit access package parameters, said package related data and executing said application software, so as to generate a thermal data simulation report based on said package data; and

a file transfer software responsive to thermal data simulation report and forward said thermal data simulation to said far-end user.

2. The system of claim 1, wherein said thermal data simulation report includes $\Theta ja = \{Tj-Ta\}/P$, wherein said Tj indicates the junction temperature, said Ta is the ambient temperature and wherein said P indicates the power dissipation.

4. The system of claim 1, wherein said thermal data simulation report includes $\Psi jt=(Tj-Tt)/P$, wherein said Tt indicates the package top center temperature, said Tj indicates the junction temperature and wherein said P indicates the power dissipation.

5. The system of claim 1, wherein said thermal data simulation report includes $\Theta jc=(Tj-Tc)/P$, wherein Tc indicates the case temperature, said Tj indicates the junction temperature and wherein said P indicates the power dissipation.

6. The system of claim 1, wherein said thermal data simulation report includes parameters of the percentage of heat dissipated from PCB (print circuit board) and package top.

7. A method for automatically providing thermal data of a semiconductor package comprising the steps of:
inputting parameters that relates to a semiconductor package by a user;
recording said parameters in a job database;
retrieving an information from said job database;
analyzing a thermal data of a package based on said parameters sent by said user;
generating a thermal data simulation report; and
forwarding said thermal data simulation report to said user through a network.

8. The method of claim 7, wherein said thermal data simulation is analyzed by a thermal analysis module.

9. The method of claim 7, wherein said thermal data simulation includes $\Theta ja=(Tj-Ta)/P$, wherein said Tj indicates the junction temperature, said Ta is the ambient temperature and wherein said P indicates the power dissipation.

10. The method of claim 7, wherein said thermal data simulation includes Ψ jt=(Tj-Tt)/P, wherein said Tt indicates the package top center temperature,said Tj indicates the junction temperature and wherein said P indicates the power dissipation.

11. The method of claim 7, wherein said thermal data simulation includes Θ jc=(Tj-Tc)/P, wherein Tc indicates the case temperature, said Tj indicates the junction temperature and wherein said P indicates the power dissipation.

12. The method of claim 7, wherein said thermal data simulation includes parameters of the percentage of heat dissipated from PCB (print circuit board) and package top.